



Pianodo Project Update Report

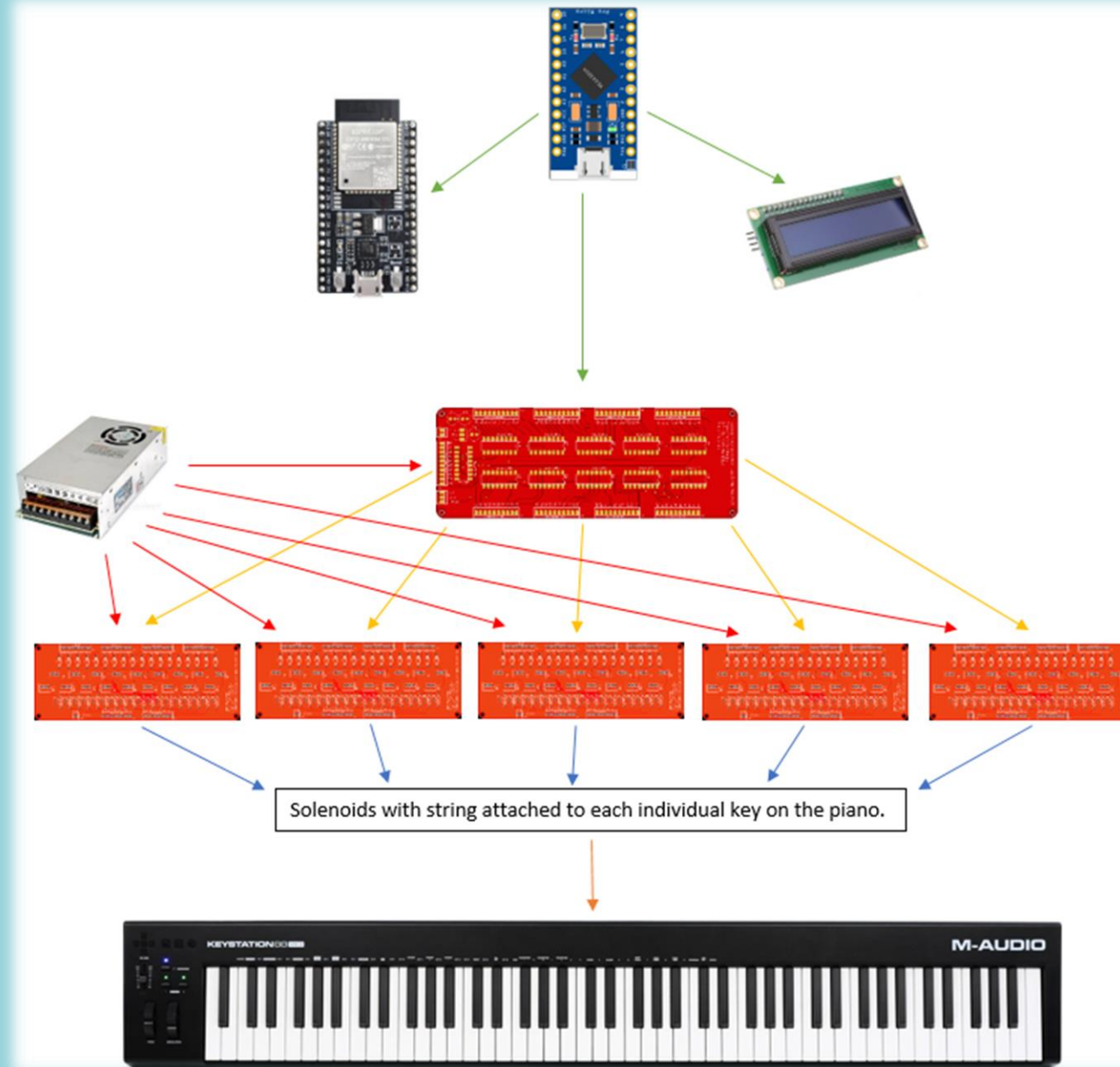
Presentation by Leonardo Fusser
Project Planning & Design
Mohamed Tavakoli

Outline

- Recap of Pianodo (re-visit)
- Arduino pro micro board overview
- ESP32 development board overview
- 16x2 with I2C module overview
- Solenoid control and control board overview
- Logic control and control board overview
- Next steps...

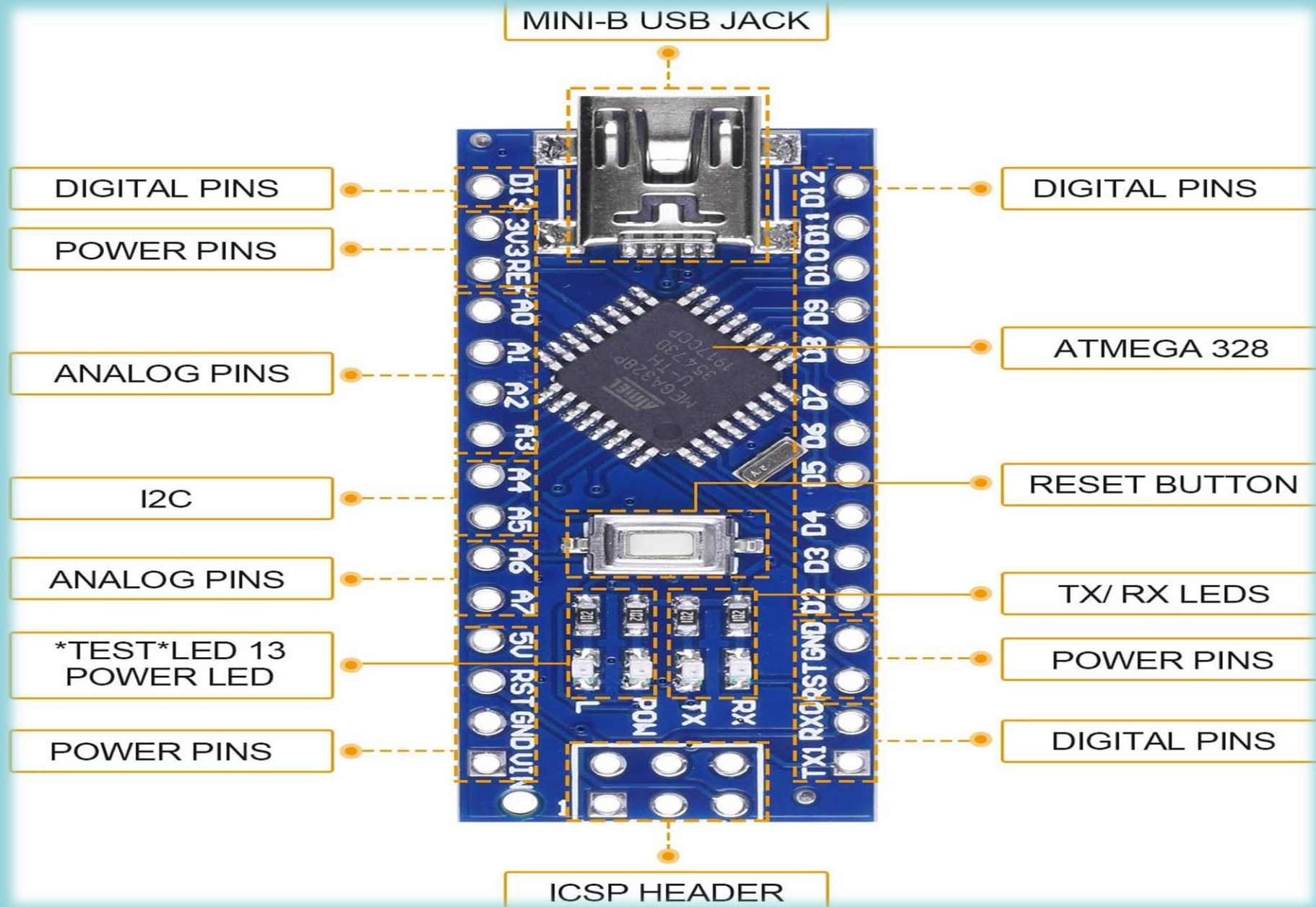
Basic overview of Pianodo

A quick look at what it is again...



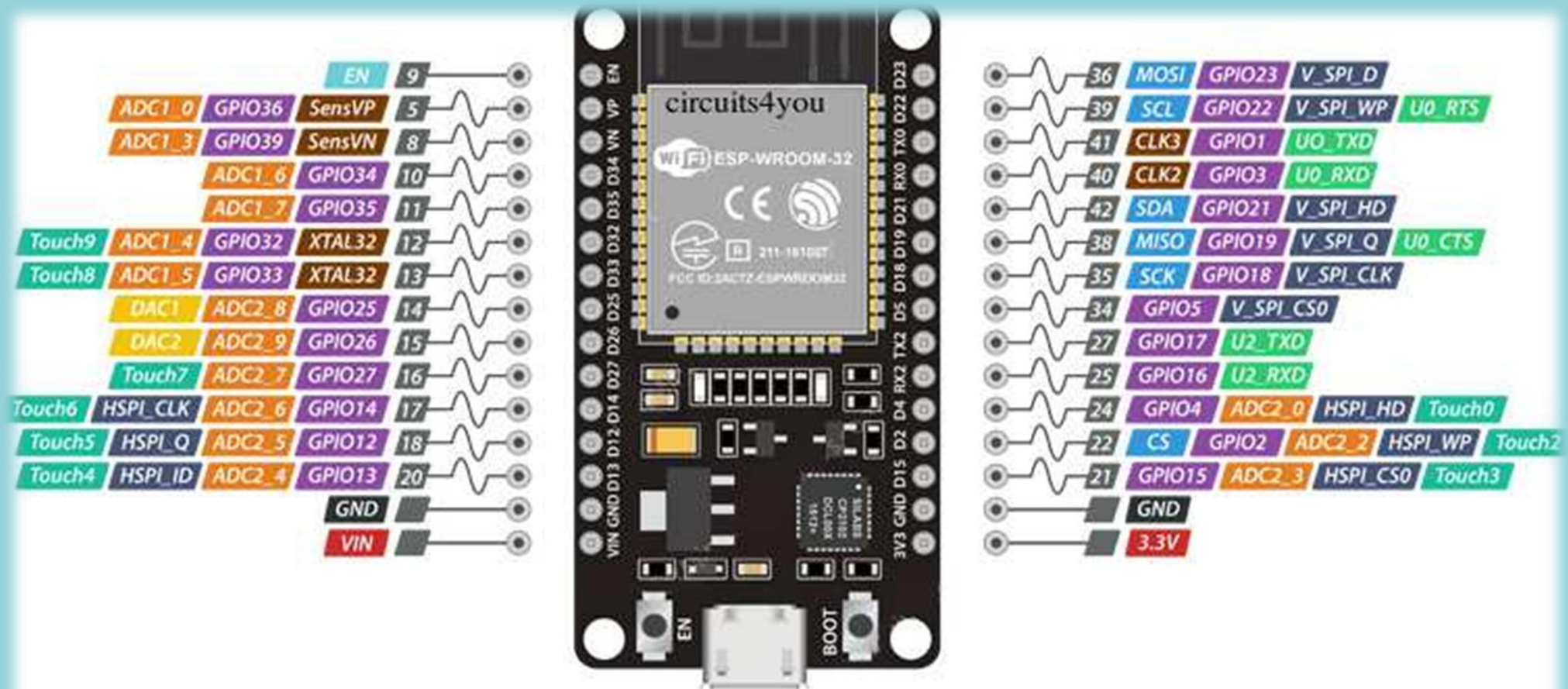
Arduino pro micro board

A quick overview of the board...



ESP32 development board

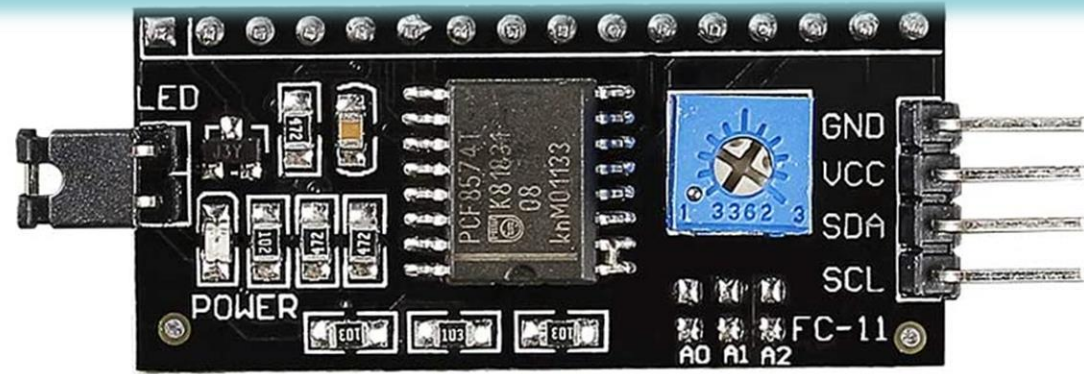
A quick overview of the board...



ESP32 Dev. Board Pinout

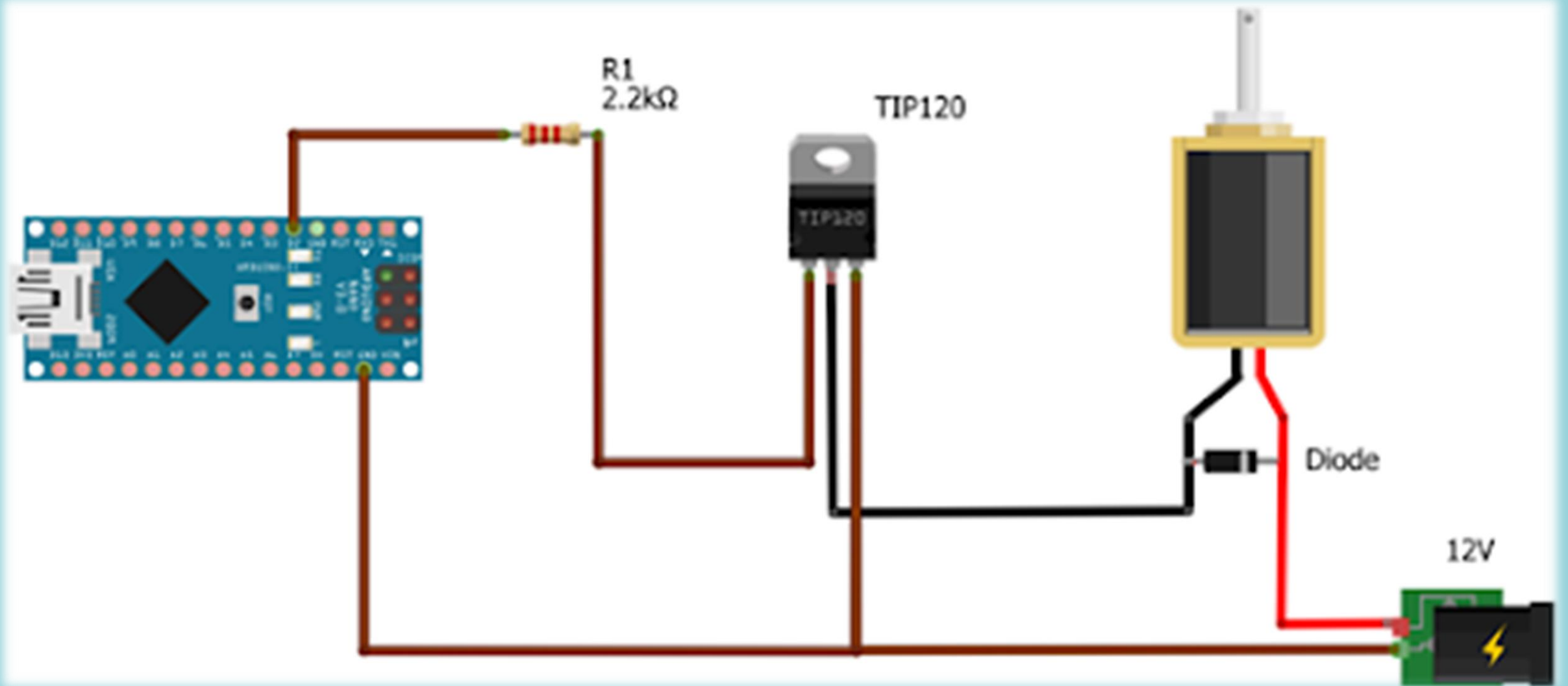
16x2 LCD with I2C module

A quick overview of the LCD display...



Solenoid control & control board overview

A quick look at how the solenoids are controlled and the PCB that holds the circuitry...



TIP120, TIP121, TIP122 (NPN); TIP125, TIP126, TIP127 (PNP)

Plastic Medium-Power Complementary Silicon Transistors

Designed for general-purpose amplifier and low-speed switching applications.

Features

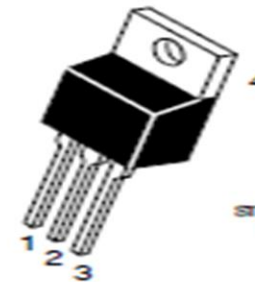
- High DC Current Gain –
 $h_{FE} = 2500$ (Typ) @ I_C
 $= 4.0$ A dc
- Collector-Emitter Sustaining Voltage – @ 100 mA dc
 $V_{CEO(sus)} = 60$ V dc (Min) – TIP120, TIP125
 $= 80$ V dc (Min) – TIP121, TIP126
 $= 100$ V dc (Min) – TIP122, TIP127
- Low Collector-Emitter Saturation Voltage –
 $V_{CE(sat)} = 2.0$ V dc (Max) @ $I_C = 3.0$ A dc
 $= 4.0$ V dc (Max) @ $I_C = 5.0$ A dc
- Monolithic Construction with Built-In Base-Emitter Shunt Resistors
- Pb-Free Packages are Available*



ON Semiconductor®

www.onsemi.com

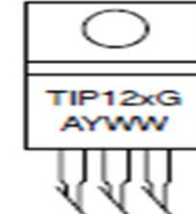
DARLINGTON 5 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 60–80–100 VOLTS, 65 WATTS



TO-220AB
CASE 221A
STYLE 1

STYLE 1:
PIN 1: BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

MARKING DIAGRAM



TIP12x = Device Code
x = 0, 1, 2, 5, 6, or 7
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

TIP120, TIP121, TIP122 (NPN); TIP125, TIP126, TIP127 (PNP)

MAXIMUM RATINGS

Rating	Symbol	TIP120, TIP125	TIP121, TIP126	TIP122, TIP127	Unit
Collector-Emitter Voltage	V_{CEO}	60	80	100	Vdc
Collector-Base Voltage	V_{CB}	60	80	100	Vdc
Emitter-Base Voltage	V_{EB}		5.0		Vdc
Collector Current – Continuous – Peak	I_C		5.0 8.0		Adc
Base Current	I_B		120		mA dc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D		65 0.52		W W/ $^\circ\text{C}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D		2.0 0.016		W W/ $^\circ\text{C}$
Unclamped Inductive Load Energy (Note 1)	E		50		mJ
Operating and Storage Junction, Temperature Range	T_J, T_{stg}		-65 to +150		$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.92	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. $I_C = 1\text{ A}$, $L = 100\text{ mH}$, P.R.F. = 10 Hz, $V_{CC} = 20\text{ V}$, $R_{BE} = 100\ \Omega$

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
----------------	--------	-----	-----	------

OFF CHARACTERISTICS

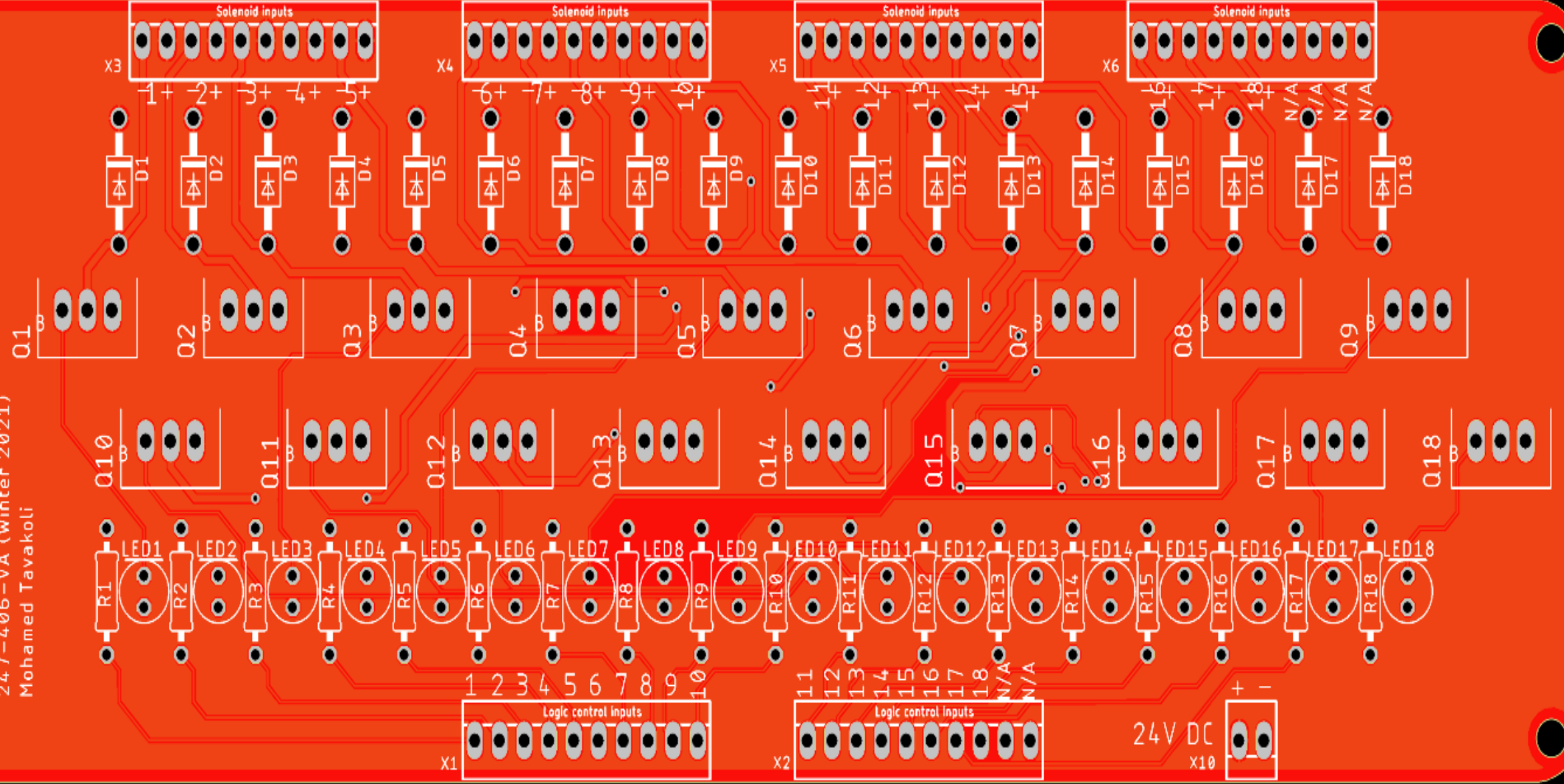
Collector-Emitter Sustaining Voltage (Note 2) ($I_C = 100\text{ mA dc}$, $I_B = 0$)	TIP120, TIP125 TIP121, TIP126 TIP122, TIP127	$V_{CEO(sus)}$	60 80 100	– – –	Vdc
Collector Cutoff Current ($V_{CE} = 30\text{ Vdc}$, $I_B = 0$) ($V_{CE} = 40\text{ Vdc}$, $I_B = 0$) ($V_{CE} = 50\text{ Vdc}$, $I_B = 0$)	TIP120, TIP125 TIP121, TIP126 TIP122, TIP127	I_{CEO}	– – –	0.5 0.5 0.5	mA dc
Collector Cutoff Current ($V_{CB} = 60\text{ Vdc}$, $I_E = 0$) ($V_{CB} = 80\text{ Vdc}$, $I_E = 0$) ($V_{CB} = 100\text{ Vdc}$, $I_E = 0$)	TIP120, TIP125 TIP121, TIP126 TIP122, TIP127	I_{CBO}	– – –	0.2 0.2 0.2	mA dc
Emitter Cutoff Current ($V_{BE} = 5.0\text{ Vdc}$, $I_C = 0$)		I_{EBO}	–	2.0	mA dc

ON CHARACTERISTICS (Note 2)

DC Current Gain ($I_C = 0.5\text{ Adc}$, $V_{CE} = 3.0\text{ Vdc}$) ($I_C = 3.0\text{ Adc}$, $V_{CE} = 3.0\text{ Vdc}$)	h_{FE}	1000 1000	– –	–
Collector-Emitter Saturation Voltage ($I_C = 3.0\text{ Adc}$, $I_B = 12\text{ mA dc}$) ($I_C = 5.0\text{ Adc}$, $I_B = 20\text{ mA dc}$)	$V_{CE(sat)}$	– –	2.0 4.0	Vdc
Base-Emitter On Voltage ($I_C = 3.0\text{ Adc}$, $V_{CE} = 3.0\text{ Vdc}$)	$V_{BE(on)}$	–	2.5	Vdc

DYNAMIC CHARACTERISTICS

Small-Signal Current Gain ($I_C = 3.0\text{ Adc}$, $V_{CE} = 4.0\text{ Vdc}$, $f = 1.0\text{ MHz}$)	h_{fe}	4.0	–	–
Output Capacitance ($V_{CB} = 10\text{ Vdc}$, $I_E = 0$, $f = 0.1\text{ MHz}$)	C_{ob}	– –	300 200	pF



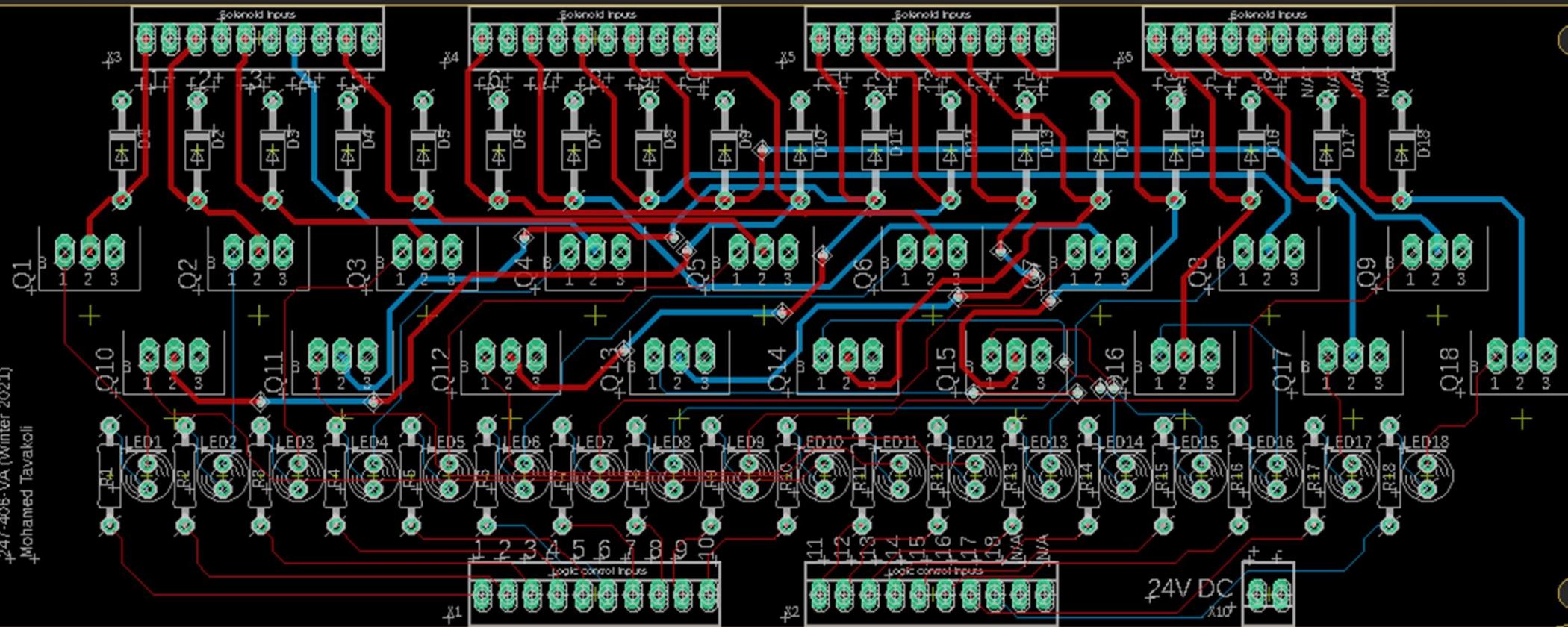
Solenoid Control Board v1.0

Leonardo Fusser (1948995)

Project Planning & Design

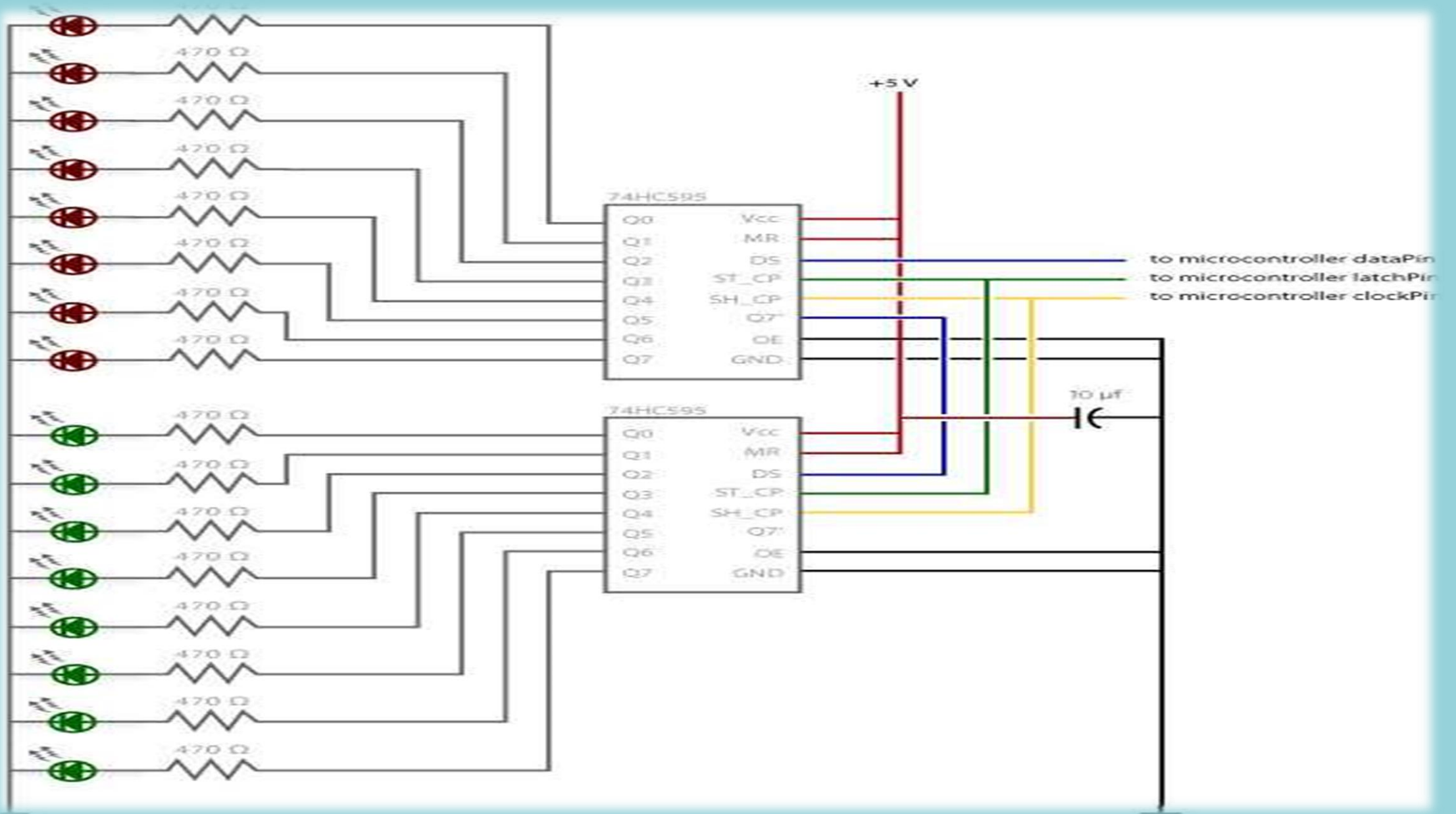
247-406-VA (Winter 2021)

Mohamed Tavakoli

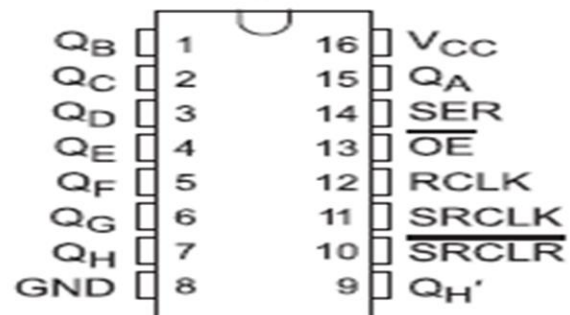


Logic control & control board overview

A quick look at how the digital logic works and the PCB that holds the circuitry...



D, N, NS, J, DB, or PW Package
16-Pin SOIC, PDIP, SO, CDIP, SSOP, or TSSOP
Top View



FK Package
20-Pin LCCC
Top View



Pin Functions

PIN			I/O	DESCRIPTION
NAME	SOIC, PDIP, SO, CDIP, SSOP, or TSSOP	LCCC		
GND	8	10	—	Ground Pin
OE	13	17	I	Output Enable
QA	15	19	O	QA Output
QB	1	2	O	QB Output
QC	2	3	O	QC Output
QD	3	4	O	QD Output
QE	4	5	O	QE Output
QF	5	7	O	QF Output
QG	6	8	O	QG Output
QH	7	9	O	QH Output
QH'	9	12	O	QH' Output
RCLK	12	14	I	RCLK Input
SER	14	18	I	SER Input
SRCLK	11	14	I	SRCLK Input
SRCLR	10	13	I	SRCLR Input
NC	—	1	—	No Connection
		16		
		11		
		16		
VCC	—	20	—	Power Pin

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		-0.5	7	V
I_{IK}	Input clamp current ⁽²⁾	$V_I < 0$ or $V_I > V_{CC}$		± 20	mA
I_{OK}	Output clamp current ⁽²⁾	$V_O < 0$ or $V_O > V_{CC}$		± 20	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}		± 35	mA
	Continuous current through V_{CC} or GND			± 70	mA
T_J	Junction temperature			150	°C
T_{stg}	Storage temperature		-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	1000	

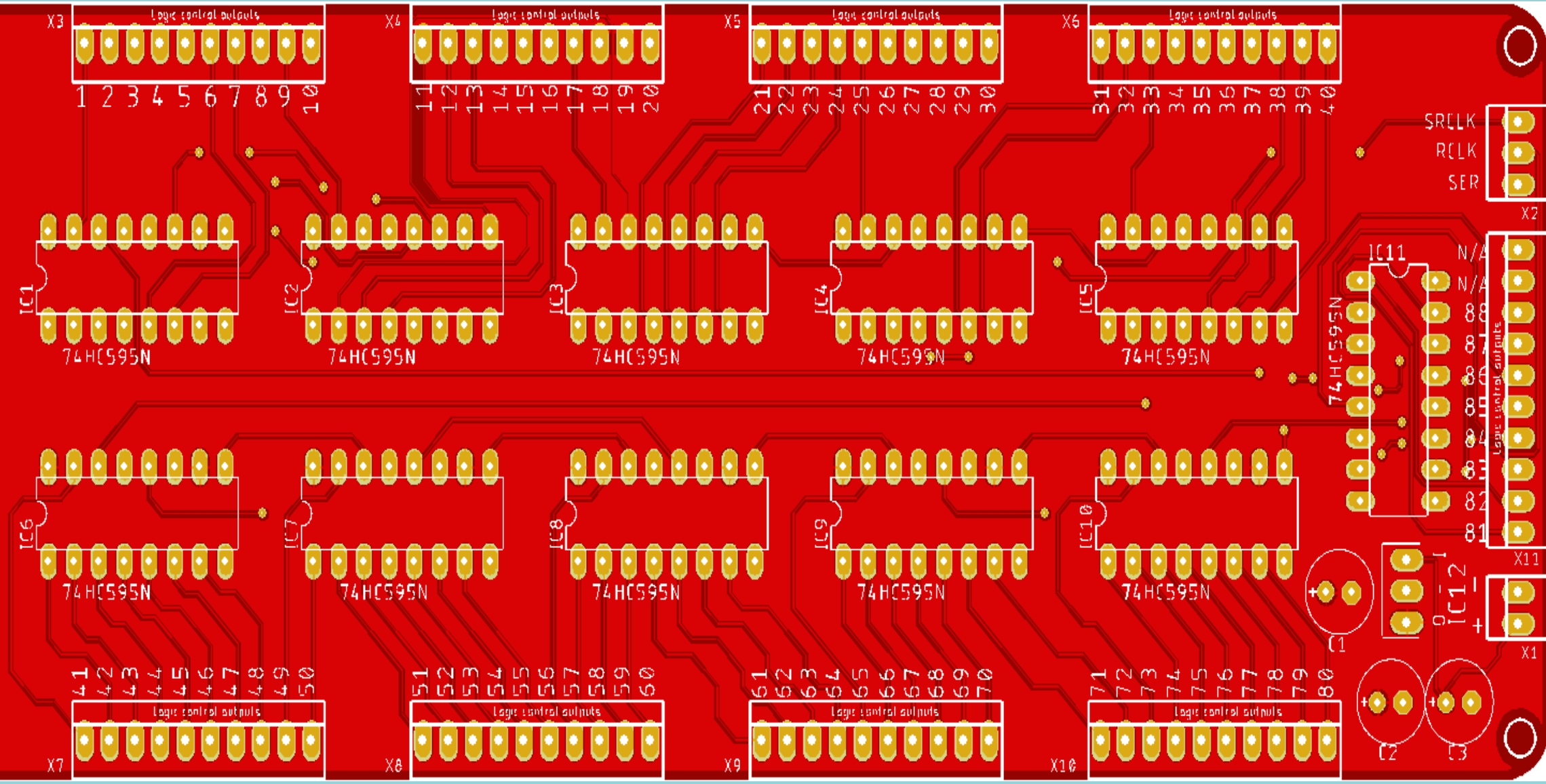
(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			SN54HC595			SN74HC595			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5			1.5			V
		$V_{CC} = 4.5$ V	3.15			3.15			
		$V_{CC} = 6$ V	4.2			4.2			
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V			0.5			0.5	V
		$V_{CC} = 4.5$ V			1.35			1.35	
		$V_{CC} = 6$ V			1.8			1.8	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
$\Delta t/\Delta v$	Input transition rise or fall time ⁽²⁾	$V_{CC} = 2$ V			1000			1000	ns
		$V_{CC} = 4.5$ V			500			500	
		$V_{CC} = 6$ V			400			400	
T_A	Operating free-air temperature		-55		125	-40		85	°C



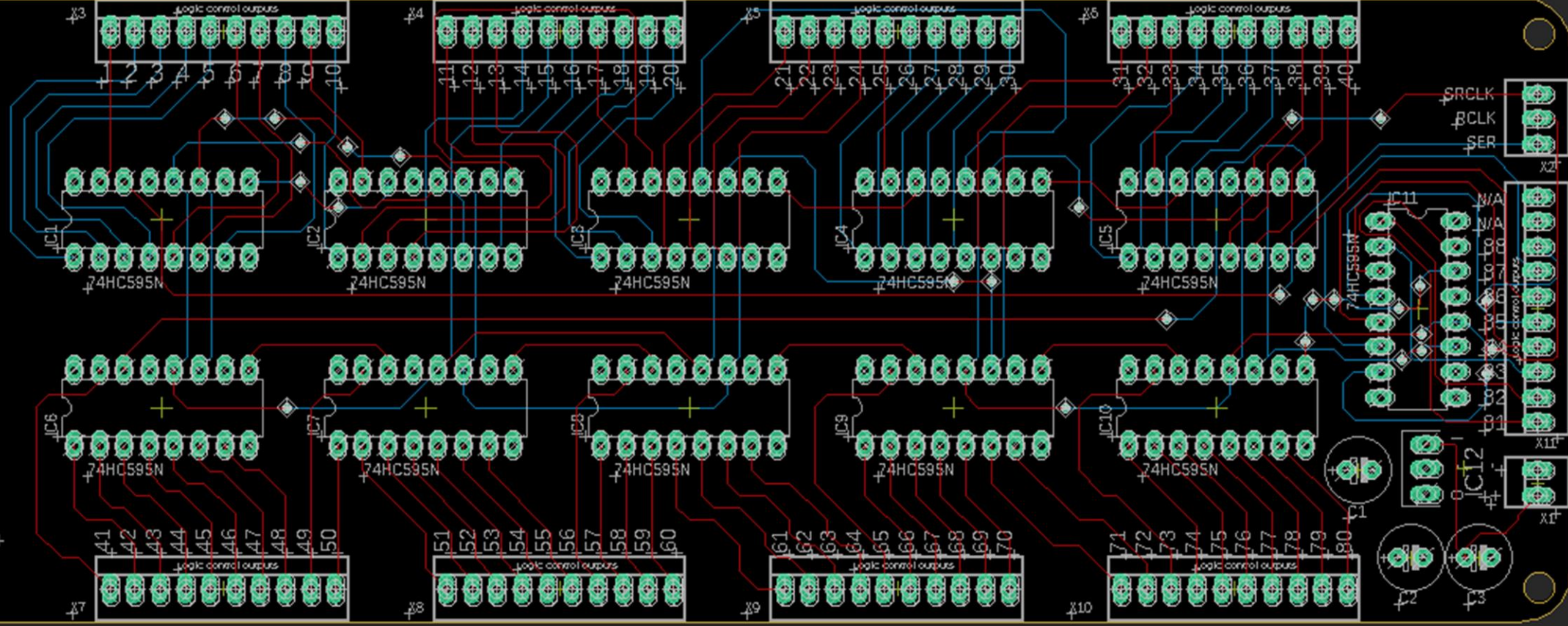
Logic Control Board v1.0

Leonardo Fusser (1946995)

Project Planning & Design

247-406-VA (Winter 2021)

Mohamed Tavakoli



Next steps

What's next for Pianodo...

Next steps

- ❖ Waiting for final electrical components to arrive.
- ❖ Assembly of all electrical components to PCBs.
- ❖ Assembly of project with electricals.
- ❖ Programming the boards.
- ❖ Esthetics and final touch-ups.